

In The Claims:

Claim 1. (original) A method of fabricating an imagine sensor device, comprising:

- providing a substrate having a plurality of trenches therein;
- forming a first anti-reflective layer on surfaces of the trenches;
- filing an insulating layer in the trenches for forming a plurality of shallow trench isolation regions;
- forming at least one photo sensitive region within the substrate between two neighboring isolation regions; and
- forming a second anti-reflective layer at least covering the photo sensitive region.

Claim 2. (original) The method of fabricating an imagine sensor device of claim 1, wherein the material of the first anti-reflective layer is selected from a group consisting of silicon nitride or silicon oxynitride.

Claim 3. (original) The method of fabricating an imagine sensor device of claim 1, wherein the step of forming the first anti-reflective layer comprises a chemical vapor deposition method.

Claim 4. (original) The method of fabricating an imagine sensor device of claim 1, wherein the material of the second anti-reflective layer is selected from a group consisting of silicon nitride or silicon oxynitride.

Claim 5. (original) The method of fabricating an imagine sensor device of claim 1, wherein the step of forming the second anti-reflective layer comprises a chemical vapor deposition method.

Claim 6. (original) The method of fabricating an imagine sensor device of claim 1, wherein the step of forming the photo sensitive region comprises performing an implantation process.

Claim 7. (original) The method of fabricating an image sensor device of claim 1, further comprising forming a liner layer on the surfaces of the trenches between the steps of providing the substrate and forming the first anti-reflective layer.

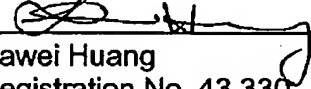
Claims 8-11 (canceled)

No fee is believed to be due in connection with the filing of this paper. However, the Commissioner is authorized to charge any additional fees that may be required to Account No. 50-0710 (Order No. JCLA11796).

Respectfully submitted,
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